

# HSB88WA

Silicon Schottky Barrier Diode for High Speed Switching

REJ03G0587-0100 (Previous: ADE-208-965) Rev.1.00 Mar 31, 2005

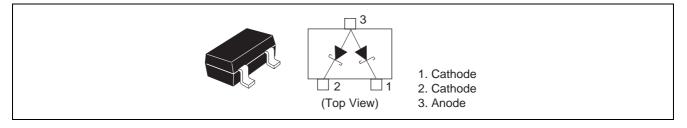
### Features

- Low reverse current, Low capacitance.
- CMPAK package is suitable for high density surface mounting and high speed assembly.

### **Ordering Information**

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSB88WA	C7	СМРАК	PTSP0003ZB-A (CMPAK)

### Pin Arrangement





## **Absolute Maximum Ratings**

### $(Ta = 25^{\circ}C)$ Symbol Value Unit ltem Reverse voltage $\mathsf{V}_\mathsf{R}$ 10 V lo \*<sup>1</sup> Average rectified current 15 mΑ 125 °C Junction temperature Tj °C Storage temperature Tstg -55 to +125

Note: 1. Per one device.

# Electrical Characteristics \*1

 $(Ta = 25^{\circ}C)$ 

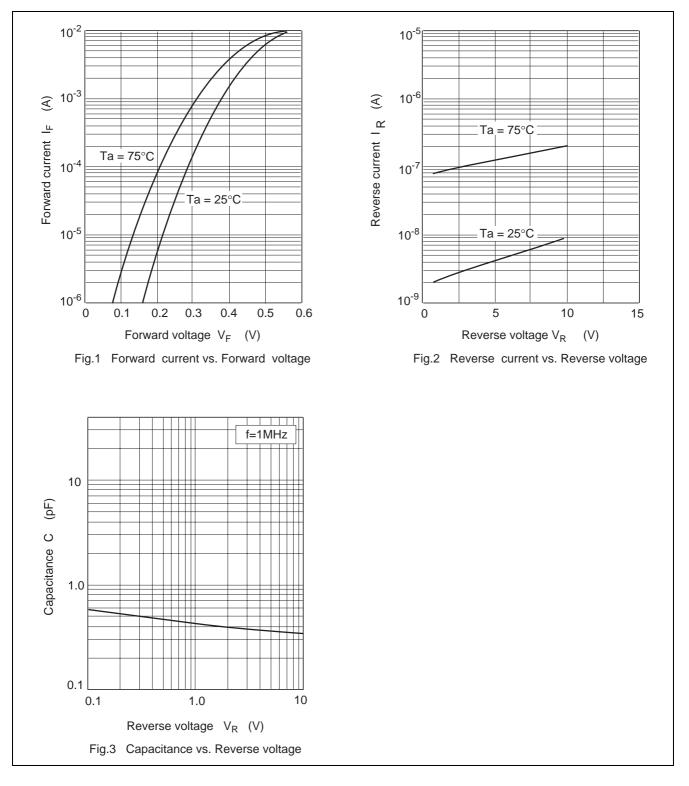
ltem	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V <sub>F1</sub>	0.350	-	0.420	V	I <sub>F</sub> = 1 mA
	V <sub>F2</sub>	0.500	-	0.580		I <sub>F</sub> = 10 mA
Reverse current	I <sub>R1</sub>			0.2	μA	V <sub>R</sub> = 2 V
	I <sub>R2</sub>	_	_	10		V <sub>R</sub> = 10 V
Capacitance	С	_	-	0.80	pF	V <sub>R</sub> = 0 V, f = 1 MHz
Capacitance deviation	ΔC	_	-	0.10	pF	V <sub>R</sub> = 0 V, f = 1 MHz
Forward voltage deviation	$\Delta V_{F}$	-	-	10	mV	I <sub>F</sub> = 10 mA
ESD-Capabilityme *2	—	30	_	_	V	C = 200 pF, R = 0 $\Omega$ , Both forward
						and reverse direction 1 pulse.

Notes: 1. Per one device.

2. Failure criterion ;  $I_R>0.4~\mu A$  at  $V_R$  = 2V

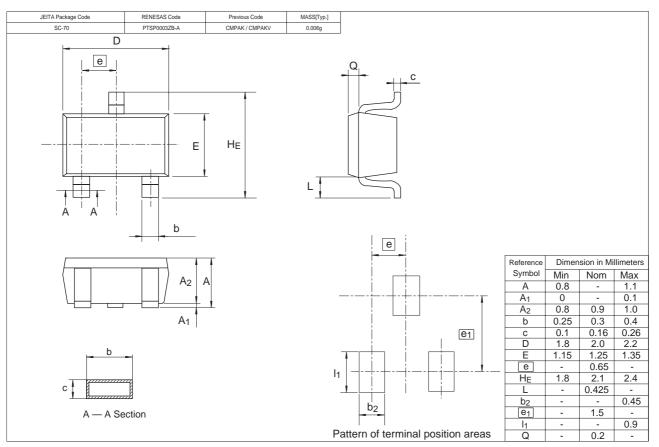


### **Main Characteristic**





### Package Dimensions





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